

PRODUCT / PROCESS CHANGE INFORMATION

1. PCI basic data

1.1 Company		STMicroelectronics International N.V
1.2 PCI No.	MDG/17/10572	
1.3 Title of PCI	New Tape Header finishing procedure for EEPROM in WLCSP	
1.4 Product Category	EEPROM in WLCSP	
1.5 Issue date	2017-11-21	

2. PCI Team

2.1 Contact supplier	
2.1.1 Name	ROBERTSON HEATHER
2.1.2 Phone	+1 8475853058
2.1.3 Email	heather.robertson@st.com
2.2 Change responsibility	
2.2.1 Product Manager	Benoit RODRIGUES
2.1.2 Marketing Manager	Hubert LEDUC
2.1.3 Quality Manager	Rita PAVANO

3. Change

3.1 Category	3.2 Type of change	3.3 Manufacturing Location
Methods	Process flow chart: Revision change in Process/Recipe like addition, deletion of process step (process technology, sawing, die attach, plasma, marking, packing, labelling, transportation, etc..)	STATSChipPAC subcontractor

4. Description of change

	Old	New
4.1 Description	- In the current situation, the header is linked to the protective belt. Then placing (at finishing step) or removing (at customer unreeling step) the protective belt could induce tension to the tape.	With the new procedure, the header is linked to itself and pasted to the protective belt (with the same ESD tape). Then, removing the protective belt will have less tension on the tape.
4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?	No impact	

5. Reason / motivation for change

5.1 Motivation	Reduction of potential tight winding of the tape.
5.2 Customer Benefit	QUALITY IMPROVEMENT

6. Marking of parts / traceability of change

6.1 Description	N/A
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7. Timing / schedule

7.1 Date of qualification results	2017-11-21
7.2 Intended start of delivery	2017-12-11
7.3 Qualification sample available?	Not Applicable

8. Qualification / Validation

8.1 Description			
8.2 Qualification report and qualification results	In progress	Issue Date	

9. Attachments (additional documentations)

10572 Public product.pdf
10572 PCI End of Tape WLCSP WITHOUT EPE- ALL CUSTOMERS -5-.pdf

10. Affected parts

10. 1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	M24C08-FCT6TP/T	
	M24C32-FCU6TP/TF	
	M24C64-FCU6TP/TF	
	M24C64M-FCU6T/TF	
	M24C64T-FCU6T/TF	



Public Products List

Public Products are off the shelf products. They are not dedicated to specific customers, they are available through ST Sales team, or Distributors, and visible on ST.com

PCI Title : New Tape Header finishing procedure for EEPROM in WLCSP

PCI Reference : MDG/17/10572

Subject : Public Products List

Dear Customer,

Please find below the Standard Public Products List impacted by the change.

M24C64T-FCU6T/TF	M24C64M-FCU6T/TF	M24C08-FCT6TP/T
M24C64-FCU6TP/TF	M24C32-FCU6TP/TF	



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